

C3D10060G

Silicon Carbide Schottky Diode

Z-REC[®] RECTIFIER

| | | |
|-------------------------------|---|-------|
| V_{RRM} | = | 600 V |
| $I_F (T_c=135^\circ\text{C})$ | = | 14 A |
| Q_c | = | 25 nC |

Features

- 600-Volt Schottky Rectifier
- Zero Reverse Recovery Current
- Zero Forward Recovery Voltage
- High-Frequency Operation
- Temperature-Independent Switching Behavior
- Extremely Fast Switching
- Positive Temperature Coefficient on V_F

Benefits

- Replace Bipolar with Unipolar Rectifiers
- Essentially No Switching Losses
- Higher Efficiency
- Reduction of Heat Sink Requirements
- Parallel Devices Without Thermal Runaway
- AEC-Q101 Qualified and PPAP Capable

Applications

- Switch Mode Power Supplies
- Power Factor Correction
 - Typical PFC P_{out} : 1000W-2000W
- Motor Drives
 - Typical Power : 3HP-5HP

Package



TO-263-2



| Part Number | Package | Marking |
|-------------|----------|----------|
| C3D10060G | TO-263-2 | C3D10060 |

Maximum Ratings ($T_c = 25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter | Value | Unit | Test Conditions | Note |
|----------------|--|------------------|------------------|---|------|
| V_{RRM} | Repetitive Peak Reverse Voltage | 600 | V | | |
| V_{RSM} | Surge Peak Reverse Voltage | 600 | V | | |
| V_{DC} | DC Blocking Voltage | 600 | V | | |
| I_F | Continuous Forward Current | 29.5 14 10 | A | $T_c=25^\circ\text{C}$ $T_c=135^\circ\text{C}$ $T_c=152^\circ\text{C}$ | |
| I_{FRM} | Repetitive Peak Forward Surge Current | 67 44 | A | $T_c=25^\circ\text{C}, t_p=10\text{ ms}, \text{Half Sine Wave}, D=0.3$ $T_c=110^\circ\text{C}, t_p=10\text{ ms}, \text{Half Sine Wave}, D=0.3$ | |
| I_{FSM} | Non-Repetitive Peak Forward Surge Current | 90 71 | A | $T_c=25^\circ\text{C}, t_p=10\text{ms}, \text{Half Sine Wave}, D=0.3$ $T_c=110^\circ\text{C}, t_p=10\text{ ms}, \text{Half Sine Wave}, D=0.3$ | |
| I_{FSM} | Non-Repetitive Peak Forward Surge Current | 250 | A | $T_c=25^\circ\text{C}, t_p=10\text{ }\mu\text{s}, \text{Pulse}$ | |
| P_{tot} | Power Dissipation | 136 59 | W | $T_c=25^\circ\text{C}$ $T_c=110^\circ\text{C}$ | |
| T_J, T_{stg} | Operating Junction and Storage Temperature | -55 to +175 | $^\circ\text{C}$ | | |

Electrical Characteristics

| Symbol | Parameter | Typ. | Max. | Unit | Test Conditions | Note |
|--------|-------------------------|-----------------|------------|---------------|--|------|
| V_F | Forward Voltage | 1.5 2.0 | 1.8 2.4 | V | $I_F = 10\text{ A}$ $T_J = 25^\circ\text{C}$ $I_F = 10\text{ A}$ $T_J = 175^\circ\text{C}$ | |
| I_R | Reverse Current | 10 20 | 50 200 | μA | $V_R = 600\text{ V}$ $T_J = 25^\circ\text{C}$ $V_R = 600\text{ V}$ $T_J = 175^\circ\text{C}$ | |
| Q_C | Total Capacitive Charge | 25 | | nC | $V_R = 600\text{ V}$, $I_F = 10\text{ A}$ $di/dt = 500\text{ A}/\mu\text{s}$ $T_J = 25^\circ\text{C}$ | |
| C | Total Capacitance | 480 50 42 | | pF | $V_R = 0\text{ V}$, $T_J = 25^\circ\text{C}$, $f = 1\text{ MHz}$ $V_R = 200\text{ V}$, $T_J = 25^\circ\text{C}$, $f = 1\text{ MHz}$ $V_R = 400\text{ V}$, $T_J = 25^\circ\text{C}$, $f = 1\text{ MHz}$ | |

Note:

1. This is a majority carrier diode, so there is no reverse recovery charge.

Thermal Characteristics

| Symbol | Parameter | Typ. | Unit |
|-----------------|--|------|---------------------------|
| $R_{\theta JC}$ | Thermal Resistance from Junction to Case | 1.2 | $^\circ\text{C}/\text{W}$ |

Typical Performance

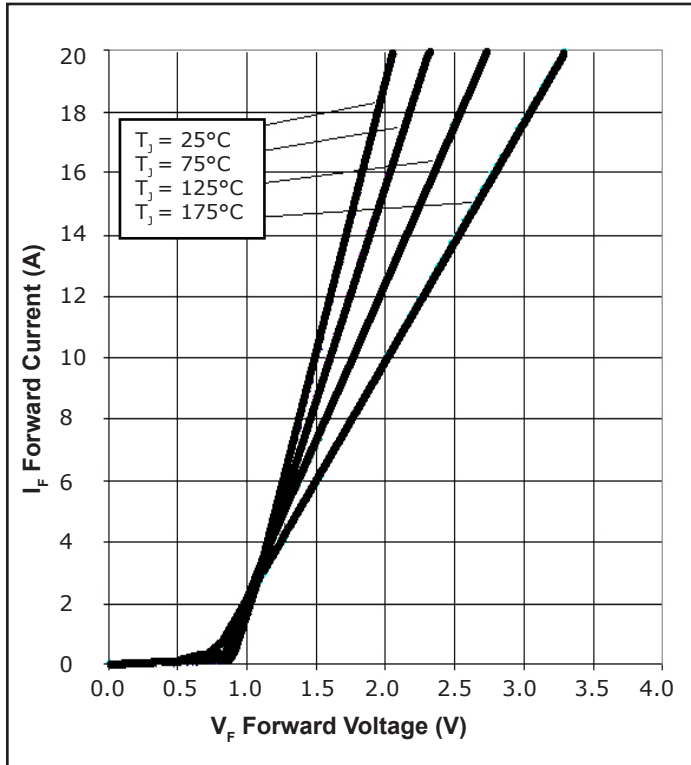


Figure 1. Forward Characteristics

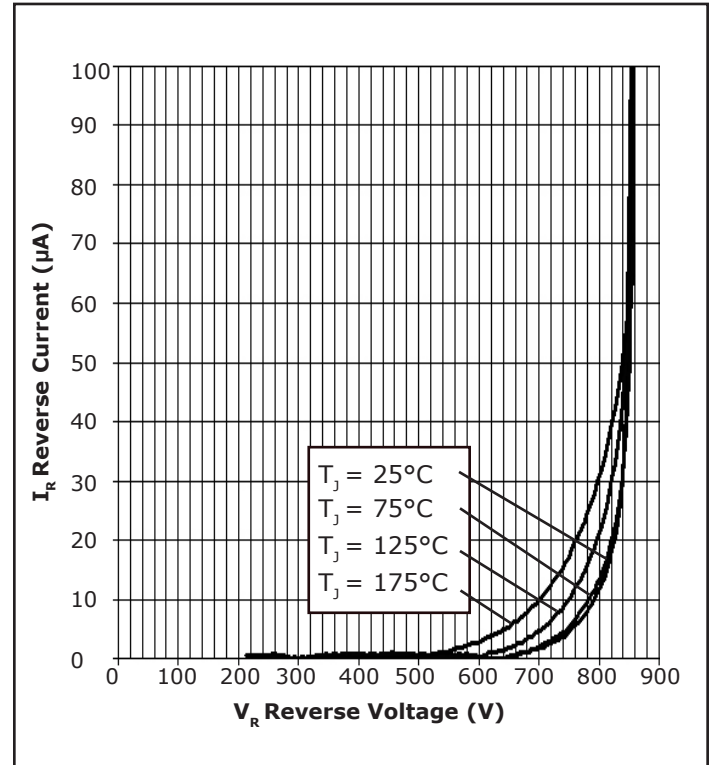


Figure 2. Reverse Characteristics

Typical Performance

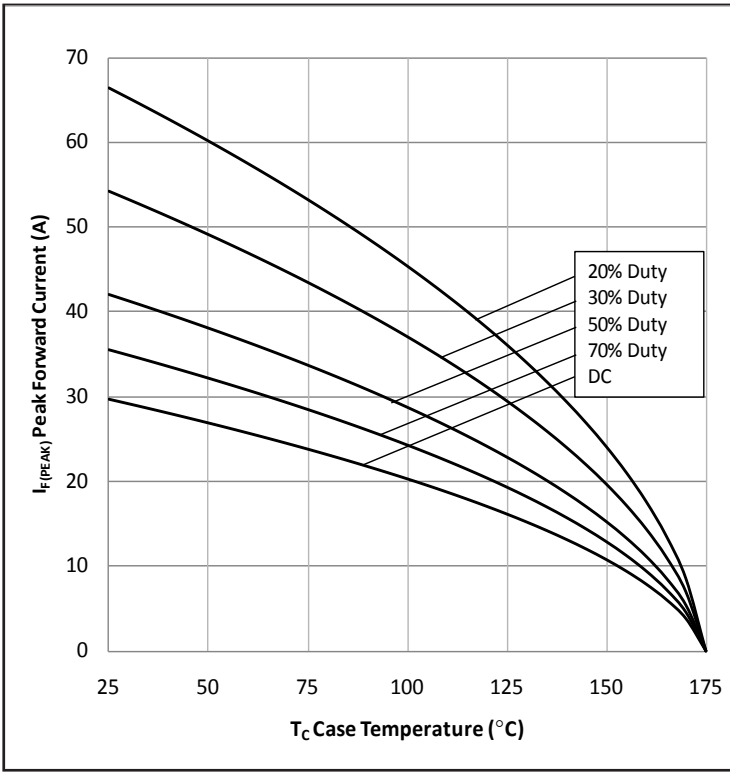


Figure 3. Current Derating

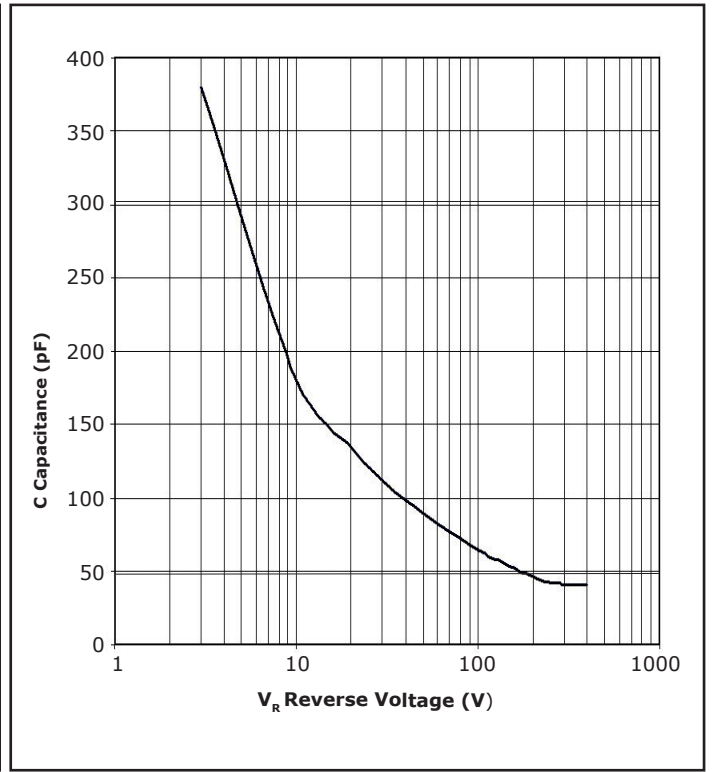


Figure 4. Capacitance vs. Reverse Voltage

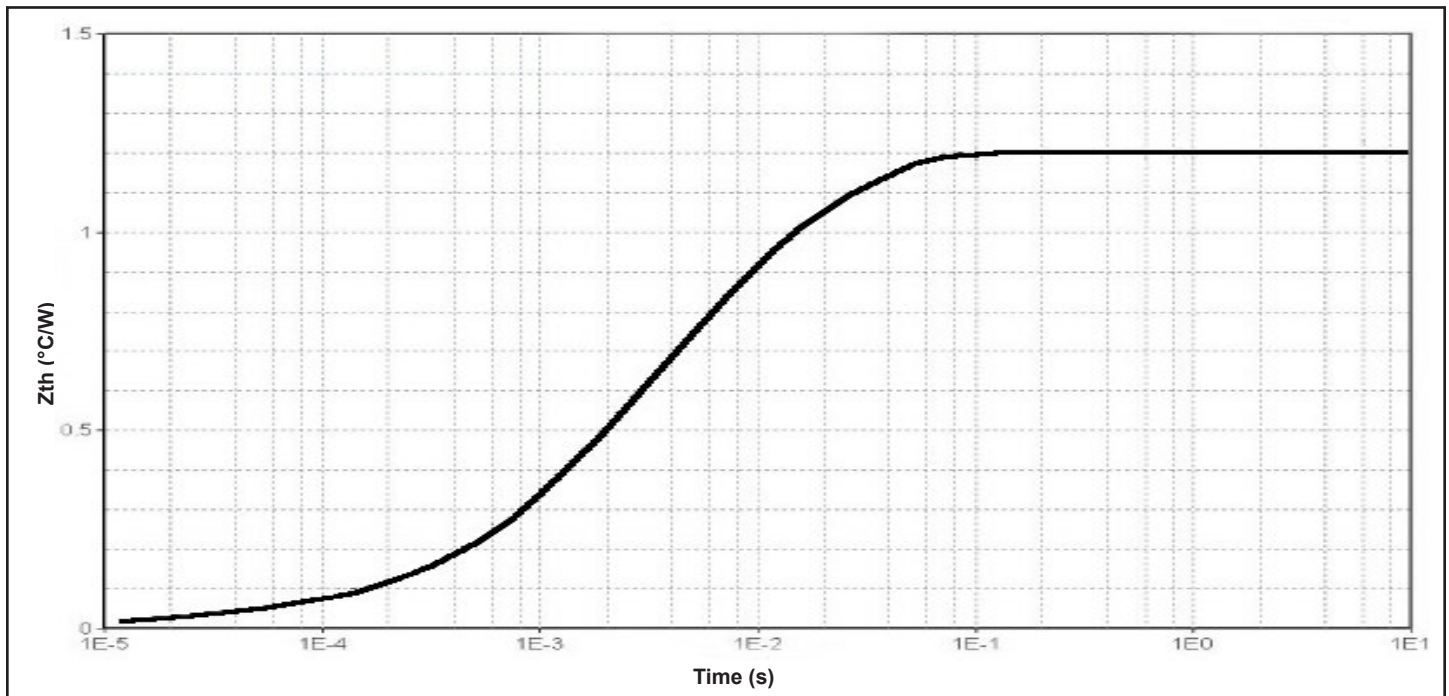


Figure 5. Transient Thermal Impedance

Typical Performance

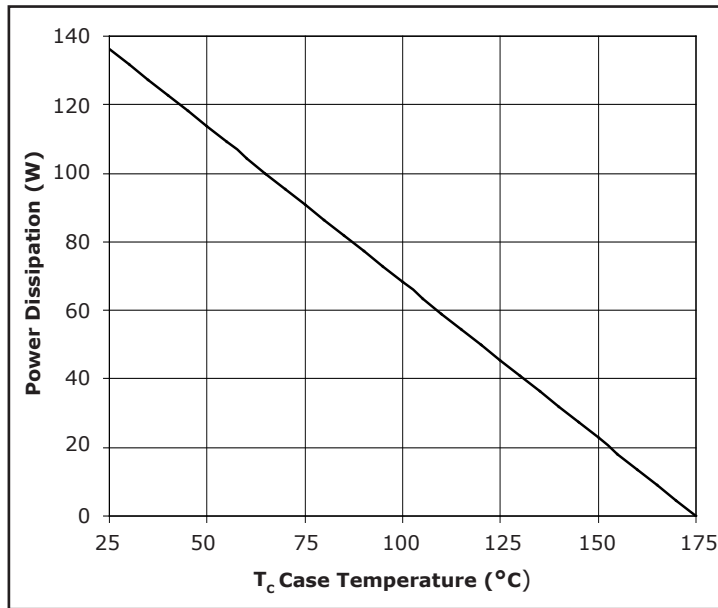
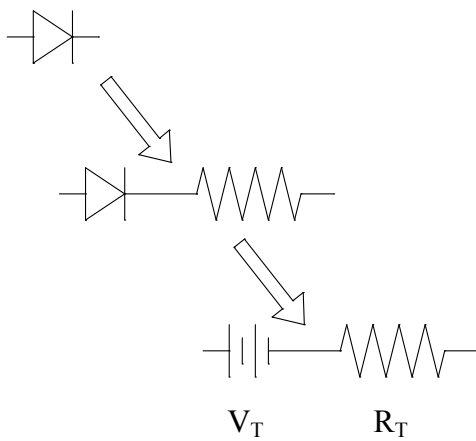


Figure 6. Power Derating

Diode Model



$$V_{f_T} = V_T + I_f \cdot R_T$$

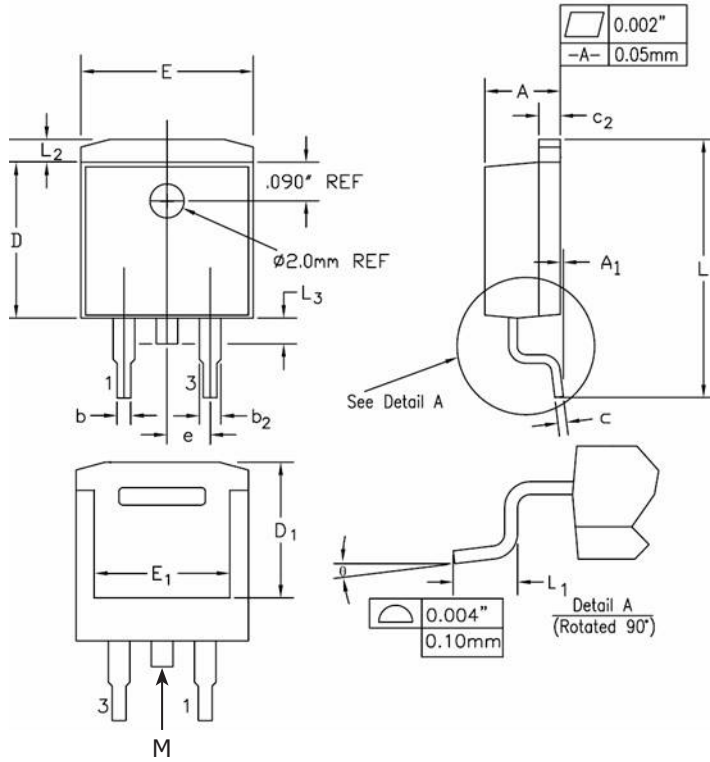
$$V_T = 0.98 + (T_j \cdot -1.6 \cdot 10^{-3})$$

$$R_T = 0.04 + (T_j \cdot 0.522 \cdot 10^{-3})$$

Note: T_j = Diode Junction Temperature In Degrees Celsius, valid from 25°C to 175°C

Package Dimensions

Package TO-263-2



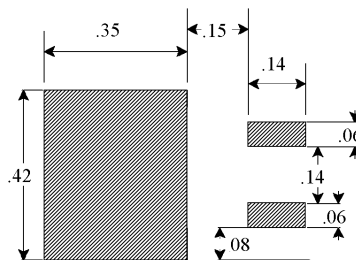
| POS | Inches | | Millimeters | |
|-----|--------|-------|-------------|-------|
| | Min | Max | Min | Max |
| A | 0.17 | 0.18 | 4.32 | 4.57 |
| A1 | - | 0.01 | - | 0.25 |
| b | 0.028 | 0.037 | 0.71 | 0.94 |
| b2 | 0.045 | 0.055 | 1.15 | 1.4 |
| c | 0.018 | 0.024 | 0.46 | 0.61 |
| c2 | 0.048 | 0.055 | 1.22 | 1.4 |
| D | 0.35 | 0.37 | 8.89 | 9.4 |
| D1 | 0.315 | 0.324 | 8.01 | 8.23 |
| E | 0.395 | 0.405 | 10.04 | 10.28 |
| E1 | 0.31 | 0.318 | 7.88 | 8.08 |
| e | 0.1 | BSC. | 2.54 | BSC. |
| L | 0.58 | 0.62 | 14.73 | 15.75 |
| L1 | 0.09 | 0.11 | 2.29 | 2.79 |
| L2 | 0.045 | 0.055 | 1.15 | 1.39 |
| L3 | 0.05 | 0.07 | 1.27 | 1.77 |
| θ | 0° | 8° | 0° | 8° |

Note:

* Tab "M" may not be present



Recommended Solder Pad Layout



TO-263-2

| Part Number | Package | Marking |
|-------------|----------|----------|
| C3D10060G | TO-263-2 | C3D10060 |

Note: Recommended soldering profiles can be found in the applications note here: http://www.cree.com/power_app_notes/soldering





Notes

- **RoHS Compliance**

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Cree representative or from the Product Documentation sections of www.cree.com.

- **REACH Compliance**

REACH substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a Cree representative to insure you get the most up-to-date REACH SVHC Declaration. REACH banned substance information (REACH Article 67) is also available upon request.

- This product has not been designed or tested for use in, and is not intended for use in, applications implanted into the human body nor in applications in which failure of the product could lead to death, personal injury or property damage, including but not limited to equipment used in the operation of nuclear facilities, life-support machines, cardiac defibrillators or similar emergency medical equipment, aircraft navigation or communication or control systems, or air traffic control systems.